

< HIGH VOLTAGE DIODE MODULES >

RM1500DC-66F

HIGH POWER SWITCHING USE
INSULATED TYPE

High Voltage Diode Modules

RM1500DC-66F



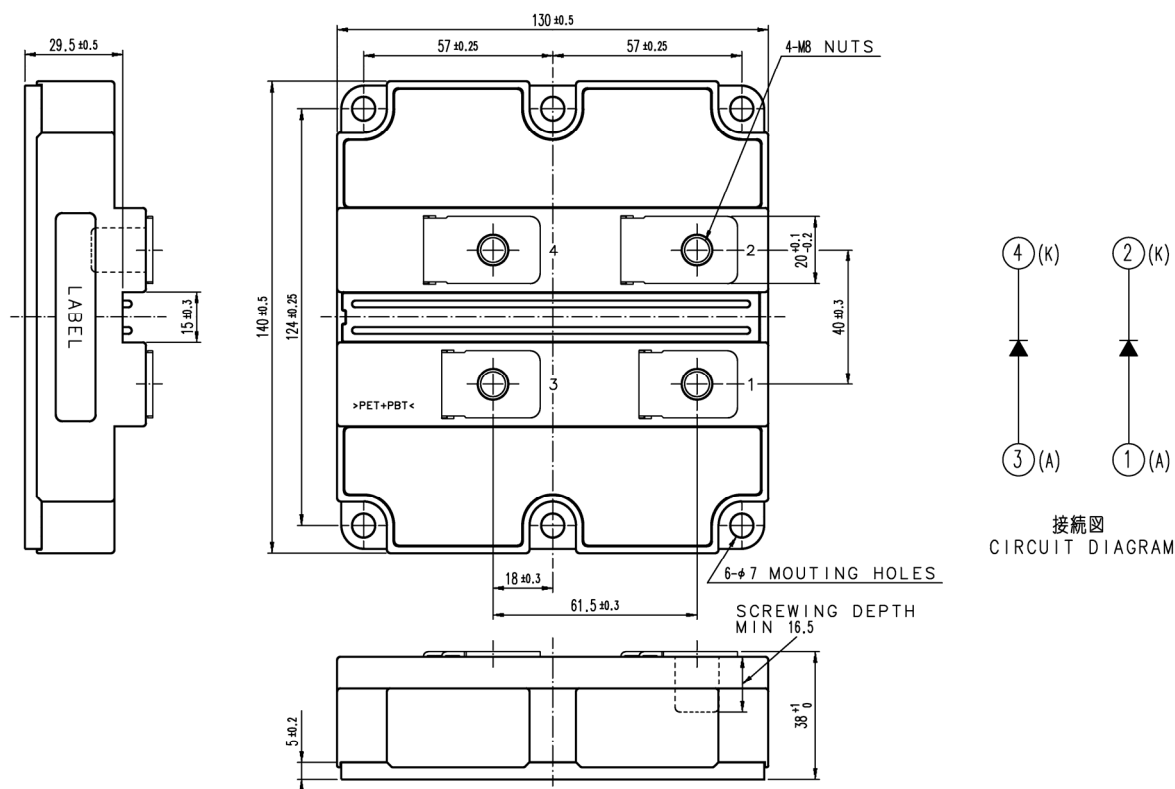
- I_F2 x 1500A
- V_{RRM}3300V
- 2-element in a Pack
- Insulated Type
- Soft Recovery Diode
- AISiC Baseplate

APPLICATION

Traction drives, High Reliability Converters / Inverters, DC choppers

OUTLINE DRAWING & CIRCUIT DIAGRAM

Dimensions in mm



RM1500DC-66FHIGH POWER SWITCHING USE
INSULATED TYPE**MAXIMUM RATINGS**

Symbol	Item	Conditions	Ratings	Unit
V_{RRM}	Repetitive peak reverse voltage	$T_j = -40 \dots +125^\circ\text{C}$	3300	V
		$T_j = -50^\circ\text{C}$	3200	
I_F	Forward current	DC, $T_c = 80^\circ\text{C}$	1500	A
I_{FSM}	Surge (non-repetitive) forward current	$T_{j_start} = 125^\circ\text{C}$, $t_p = 10$ ms, Half-sine wave, $V_R = 0$ V	14.0	kA
I_t^2	Surge current load integral		980	kA^2s
P_{tot}	Maximum power dissipation	$T_c = 25^\circ\text{C}$	7800	W
V_{iso}	Isolation voltage	RMS, sinusoidal, $f = 60$ Hz, $t = 1$ min.	6000	V
V_e	Partial discharge extinction voltage	RMS, sinusoidal, $f = 60$ Hz, $Q_{PD} \leq 10$ pC	2600	V
T_j	Junction temperature		$-50 \sim +150$	$^\circ\text{C}$
T_{jop}	Operating junction temperature		$-50 \sim +150$	$^\circ\text{C}$
T_{stg}	Storage temperature		$-55 \sim +150$	$^\circ\text{C}$

ELECTRICAL CHARACTERISTICS

Symbol	Item	Conditions		Limits			Unit
				Min	Typ	Max	
I _{RRM}	Repetitive reverse current	V _{RM} = V _{RRM}	T _J = 25°C	—	—	2.0	mA
			T _J = 125°C	—	2.0	—	
			T _J = 150°C	—	12.0	—	
V _{FM}	Forward voltage	I _F = 1500 A	T _J = 25°C	—	2.20	—	V
			T _J = 125°C	—	2.40	2.90	
			T _J = 150°C	—	2.35	—	
t _{rr}	Reverse recovery time	V _{CC} = 1800 V I _F = 1500 A -d _I F/d _t = 5500 A/μs @ T _J = 25°C 5200 A/μs @ T _J = 125°C 5100 A/μs @ T _J = 150°C L _S = 100 nH Inductive load	T _J = 25°C	—	0.65	—	μs
			T _J = 125°C	—	0.85	—	
			T _J = 150°C	—	0.95	—	
I _{rr}	Reverse recovery current		T _J = 25°C	—	1200	—	A
			T _J = 125°C	—	1450	—	
			T _J = 150°C	—	1500	—	
Q _{rr}	Reverse recovery charge		T _J = 25°C	—	1000	—	μC
			T _J = 125°C	—	1650	—	
			T _J = 150°C	—	1950	—	
E _{rec(10%)}	Reverse recovery energy ^(Note 1)	T _J = 25°C	—	1.05	—	J	
		T _J = 125°C	—	1.75	—		
		T _J = 150°C	—	2.00	—		
E _{rec}	Reverse recovery energy	T _J = 25°C	—	1.20	—	J	
		T _J = 125°C	—	2.00	—		
		T _J = 150°C	—	2.30	—		

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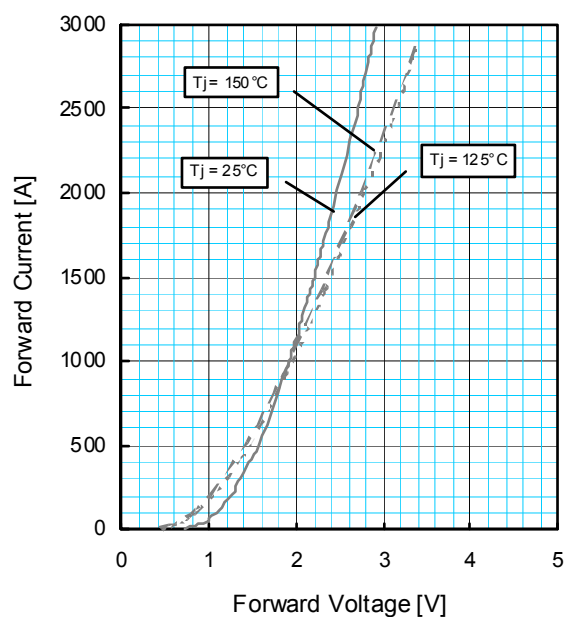
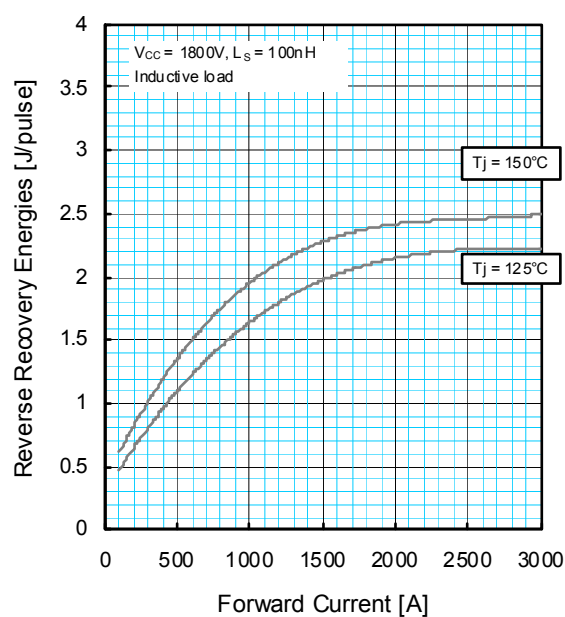
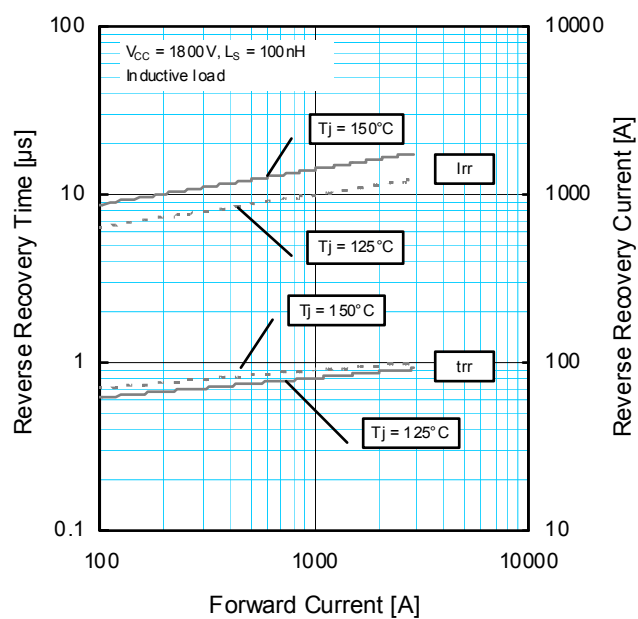
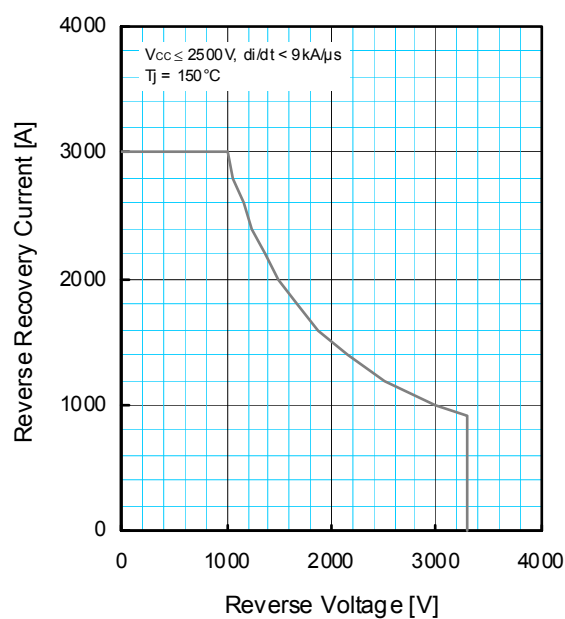
THERMAL CHARACTERISTICS

Symbol	Item	Conditions	Limits			Unit
			Min	Typ	Max	
$R_{th(j-c)}$	Thermal resistance	Junction to Case (per 1/2 module)	—	—	16.0	K/kW
$R_{th(c-s)}$	Contact thermal resistance	Case to heat sink, $\lambda_{grease} = 1 \text{ W/m}^2\text{K}$ $D_{(c-s)} = 100 \text{ }\mu\text{m}$ (per 1/2 module)	—	17.5	—	K/kW

MECHANICAL CHARACTERISTICS

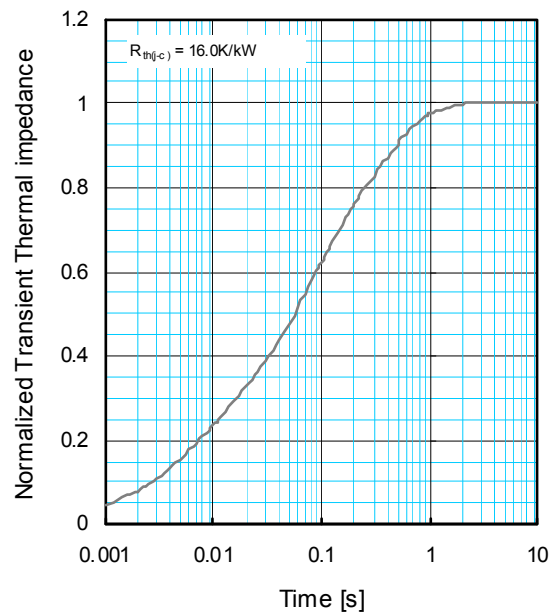
Symbol	Item	Conditions	Limits			Unit
			Min	Typ	Max	
M_t	Mounting torque	M8 : Main terminals screw	7.0	—	22.0	N·m
M_s		M6 : Mounting screw	3.0	—	6.0	N·m
m	Mass		—	0.8	—	kg
CTI	Comparative tracking index		600	—	—	—
d_a	Clearance		19.5	—	—	mm
d_s	Creepage distance		32.0	—	—	mm
$L_{P\text{ AK}}$	Parasitic stray inductance	1/2 module	—	33.0	—	nH
$R_{AA'+KK'}$	Internal lead resistance	$T_c = 25^\circ\text{C}$, 1/2 module	—	0.14	—	mΩ

Note 1. $E_{rec(10\%)}$ is the integral of $0.1V_R \times 0.1I_F \times dt$.

RM1500DC-66FHIGH POWER SWITCHING USE
INSULATED TYPE**PERFORMANCE CURVES****FORWARD CHARACTERISTICS
(TYPICAL)****REVERSE RECOVERY ENERGY
CHARACTERISTICS (TYPICAL)****REVERSE RECOVERY
CHARACTERISTICS (TYPICAL)****REVERSE RECOVERY
SAFE OPERATING AREA (RRSOA)**

PERFORMANCE CURVES

TRANSIENT THERMAL IMPEDANCE
CHARACTERISTICS



$$Z_{th(j-c)}(t) = \sum_{i=1}^n R_i \left\{ 1 - \exp\left(-\frac{t}{\tau_i}\right) \right\}$$

	1	2	3	4
R_i [K/kW] :	0.0096	0.1893	0.4044	0.3967
τ_i [sec] :	0.0001	0.0058	0.0602	0.3512

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